



*national polymer laboratories*

801 Brecksville Rd. Suite 125

Independence, Oh 44131

Office: 800.679.0477

email us at:

TechnicalService@*nationalpolymerlabs.com*.

Or call us 24/7 at:

1-800-679-0477

[www.nationalpolymerlabs.com](http://www.nationalpolymerlabs.com)

P200CA-001

01-Dec-2006

**Nanosperse P200CA** performance booster is designed to enhance the critical properties of **conductive adhesives**. Conductive adhesives are used to bond electronic components. These components find use in a wide variety of applications. Conductive adhesive bonds often fail as a result of thermal and electrical stresses derived from electrical currents. By designing strong, thermally stable polymeric systems, and combining them with well dispersed, finely divided, conductive particles, significant performance improvements can be realized.

Unlike many performance boosters, Nanospense conductive adhesive additives should be used at concentrations greater than 50%. This is necessary in order to maintain conductivity.

Nanosperse P200CA is a highly conductive, stable adhesive with good bond strength.

Percent Solids = 100%

Viscosity =

Filler particle size < 1 micron.

Critical property data for Nanospense P200CA is given below:

Resistivity =  $10^{-3}$  ohm-cm at 25°C

Tensile Strength (GPa) = 0.007 GPa to gold surface.

Cleanliness is critical to many high performance electronics applications. Nanospense P200CA is designed without solvents, inhibitors, or curing agents.